ON Semiconductor

Is Now



To learn more about onsemi™, please visit our website at www.onsemi.com

onsemi and ONSEMI. and other names, marks, and brands are registered and/or common law trademarks of Semiconductor Components Industries, LLC dba "onsemi" or its affiliates and/or subsidiaries in the United States and/or other countries. onsemi owns the rights to a number of patents, trademarks, copyrights, trade secrets, and other intellectual property. A listing of onsemi product/patent coverage may be accessed at www.onsemi.com/site/pdf/Patent-Marking.pdf. onsemi reserves the right to make changes at any time to any products or information herein is provided "as-is" and onsemi makes no warranty, representation or guarantee regarding the accuracy of the information, product features, availability, functionality, or suitability of its products for any particular purpose, nor does onsemi assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. Buyer is responsible for its products and applications using onsemi products, including compliance with all laws, regulations and safety requirements or standards, regardless of any support or applications information provided by onsemi. "Typical" parameters which may be provided in onsemi data sheets and/ or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. onsemi does not convey any license under any of its intellectual property rights nor the rights of others. onsemi products are not designed, intended, or authorized for use as a critical component in life support systems or any FDA Class 3 medical devices or medical devices with a same or similar classification in a foreign jurisdiction or any devices intended for implantation in the human body. Should Buyer purchase or use onsemi products for any such unintended or unauthorized application,

MUR210

Preferred Device

SWITCHMODE [™] **Power Rectifier**

SWITCHMODE power rectifiers are state-of-the-art devices that are designed for use in switching power supplies, inverters and as free wheeling diodes.

Features

- Ultrafast 20 Nanosecond Recovery Times
- 175°C Operating Junction Temperature
- Low Forward Voltage
- Low Leakage Current
- High Temperature Glass Passivated Junction
- These are Pb–Free Devices*

Mechanical Characteristics

- Case: Epoxy, Molded
- Weight: 0.4 Gram (Approximately)
- Finish: All External Surfaces Corrosion Resistant and Terminal Leads are Readily Solderable
- Lead and Mounting Surface Temperature for Soldering Purposes: 220°C Max for 10 Seconds, 1/16" from Case
- Polarity: Cathode Indicated by Polarity Band

MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V _{RRM} V _{RWM} V _R	100 -	٧
Average Rectified Forward Current (Square Wave Mounting Method #3) (Note 1)	I _{F(AV)}	2.0 @ T _A = 100°C	А
Non-Repetitive Peak Surge Current (Surge applied at rated load conditions halfwave, single phase, 60 Hz)	ns I _{FSM}		Α
Operating Junction Temperature and Storage Temperature Range			°C

THERMAL CHARACTERISTICS

Characteristic	Symbol	Value	Unit
Maximum Thermal Resistance, Junction–to–Ambient	$R_{\theta JA}$	See Note 3	°C/W

Maximum ratings are those values beyond which device damage can occur. Maximum ratings applied to the device are individual stress limit values (not normal operating conditions) and are not valid simultaneously. If these limits are exceeded, device functional operation is not implied, damage may occur and reliability may be affected.

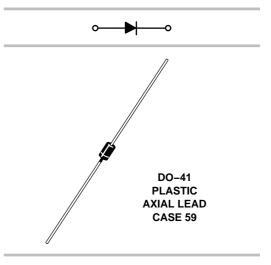
1. Pulse Test: Pulse Width = 300 μs, Duty Cycle ≤ 2.0%.



ON Semiconductor®

http://onsemi.com

ULTRAFAST RECTIFIERS2 AMPERES, 100 VOLTS



MARKING DIAGRAM



A = Assembly Location

Y = Year

WW = Work Week

= Pb-Free Package

(Note: Microdot may be in either location)

ORDERING INFORMATION

Device	Package	Shipping [†]
MUR210	Axial Lead*	1000 Units/Bag
MUR210G	Axial Lead*	1000 Units/Bag
MUR210RL	Axial Lead*	5000/Tape & Reel
MUR210RLG	Axial Lead*	5000/Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

*This package is inherently Pb-Free.

Preferred devices are recommended choices for future use and best overall value.

^{*}For additional information on our Pb–Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

MUR210

ELECTRICAL CHARACTERISTICS

Characteristic	Symbol	Value	Unit
Maximum Instantaneous Forward Voltage (Note 2) $ \begin{aligned} (I_F = 2.0 \text{ A, } T_J = 150^{\circ}\text{C}) \\ (I_F = 2.0 \text{ A, } T_J = 25^{\circ}\text{C}) \end{aligned} $	V _F	0.74 0.94	V
Maximum Instantaneous Reverse Current (Note 2) (Rated DC Voltage, T_J = 150°C) (Rated DC Voltage, T_J = 25°C)	i _R	50 2.0	μΑ
Maximum Reverse Recovery Time $ \begin{aligned} (I_F = 1.0 \text{ A, di/dt} = 50 \text{ A/}\mu\text{s}) \\ (I_F = 0.5 \text{ A, }I_R = 1.0 \text{ A, }I_{REC} = 0.25 \text{ A}) \end{aligned} $	t _{rr}	30 20	ns
Maximum Forward Recovery Time (I _F = 1.0 A, di/dt = 100 A/ μ s, I _{REC} to 1.0 V)	t _{fr}	20	ns

^{2.} Pulse Test: Pulse Width = 300 μs, Duty Cycle ≤ 2.0%.

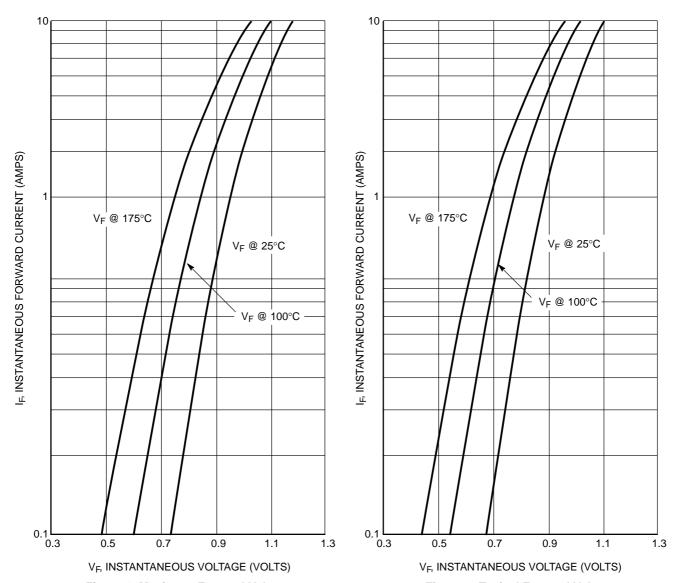


Figure 1. Maximum Forward Voltage

Figure 2. Typical Forward Voltage

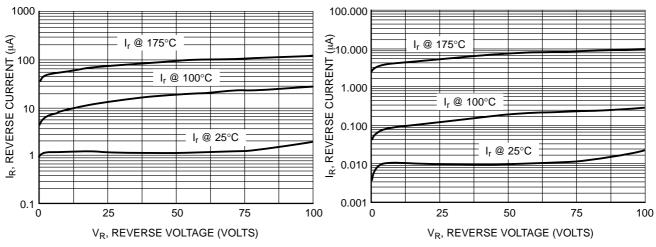


Figure 3. Maximum Reverse Current

Figure 4. Typical Reverse Current

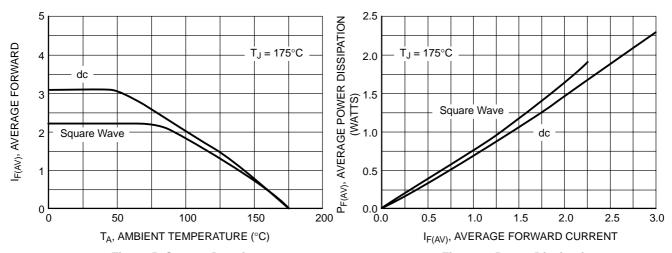


Figure 5. Current Derating

Figure 6. Power Dissipation

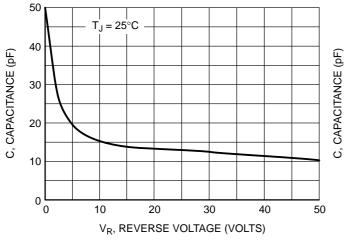


Figure 7. Maximum Capacitance

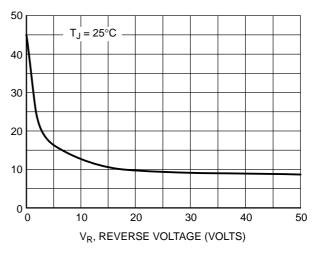


Figure 8. Typical Capacitance

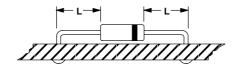
NOTE 3 – AMBIENT MOUNTING DATA

Data shown for thermal resistance junction to ambient $(R_{\theta JA})$ for the mountings shown is to be used as typical guideline values for preliminary engineering or in case the tie point temperature cannot be measured.

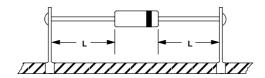
TYPICAL VALUES FOR $R_{\theta \text{JA}}$ IN STILL AIR

	Mounting Method		Lead Length, L			
			1/8	1/4	1/2	Units
	1		52	65	72	°C/W
ľ	2	$R_{\theta JA}$	67	80	87	°C/W
ľ	3			50		°C/W

MOUNTING METHOD 1

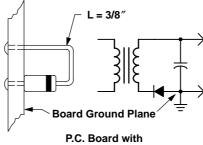


MOUNTING METHOD 2



Vector Pin Mounting

MOUNTING METHOD 3

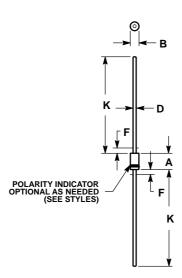


1–1/2" X 1–1/2" Copper Surface

MUR210

PACKAGE DIMENSIONS

AXIAL LEAD CASE 59-10 ISSUE U



NOTES:

- 1. DIMENSIONING AND TOLERANCING PER ANSI Y14 5M 1982
- Y14.5M, 1982.
 CONTROLLING DIMENSION: INCH.
 ALL RULES AND NOTES ASSOCIATED WITH
 JEDEC DO-41 OUTLINE SHALL APPLY
 POLARITY DENOTED BY CATHODE BAND.
 LEAD DIAMETER NOT CONTROLLED WITHIN F
- DIMENSION.

	INCHES		MILLIMETERS		
DIM	MIN	MAX	MIN	MAX	
Α	0.161	0.205	4.10	5.20	
В	0.079	0.106	2.00	2.70	
D	0.028	0.034	0.71	0.86	
F		0.050		1.27	
K	1.000		25.40		

SWITCHMODE is a trademark of Semiconductor Components Industries, LLC.

ON Semiconductor and un are registered trademarks of Semiconductor Components Industries, LLC (SCILLC). SCILLC reserves the right to make changes without further notice on semiconductor and are registered readerlands of semiconductor Components industries, Ltc (SCILLC) solicit esserves the inject to any products herein. SCILLC makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does SCILLC assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. "Typical" parameters which may be provided in SCILLC data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. SCILLC does not convey any license under its patent rights nor the rights of others. SCILLC products are not designed, intended, or authorized for use as components in systems intended for surgical implant into the body, or other applications intended to support or sustain life, or for any other application in which the failure of the SCILLC product could create a situation where personal injury or death may occur. Should Buyer purchase or use SCILLC products for any such unintended or unauthorized application, Buyer shall indemnify and hold SCILLC and its officers, employees, subsidiaries, affiliates, and distributors harmless against all claims, costs, damages, and expenses, and reasonable attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized use, even if such claim alleges that SCILLC was negligent regarding the design or manufacture of the part. SCILLC is an Equal Opportunity/Affirmative Action Employer. This literature is subject to all applicable copyright laws and is not for resale in any manner.

PUBLICATION ORDERING INFORMATION

LITERATURE FULFILLMENT:

Literature Distribution Center for ON Semiconductor P.O. Box 61312, Phoenix, Arizona 85082-1312 USA Phone: 480-829-7710 or 800-344-3860 Toll Free USA/Canada Fax: 480-829-7709 or 800-344-3867 Toll Free USA/Canada Email: orderlit@onsemi.com

N. American Technical Support: 800-282-9855 Toll Free

Japan: ON Semiconductor, Japan Customer Focus Center 2-9-1 Kamimeguro, Meguro-ku, Tokyo, Japan 153-0051 Phone: 81-3-5773-3850

ON Semiconductor Website: http://onsemi.com

Order Literature: http://www.onsemi.com/litorder

For additional information, please contact your local Sales Representative.